

T-4909-AE

40
YEARS
ANNIVERSARY
EDITION

For the past 40 years, Dr. Tresky AG has been perfecting the art of creating die bonding / pick & place systems.

The **T-4909-AE anniversary edition** is a manual, budget sensitive die bonder with superior ergonomic design. As with all of Tresky's products, the **T-4909-AE** incorporates True Vertical Technology™ which guarantees parallelism between chip and substrate at any bond height. Bonding parameters and sequences, intuitively programmable by an integrated Raspberry PC with touchscreen.

T-4909-AE Application Packages:

- Epoxy
- Eutectic
- Flip-Chip

Force controlled

True Vertical Technology™

Easy to use

MICRO ASSEMBLY

T-4909-AE



TRESKY

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Excellent performance, ergonomically designed and high reliability makes the **T-4909-AE** ideal for small and medium volume production.

APPLICATIONS

Die Attach, Flip-Chip, MEMS, MOEMS, VCSEL, RFID, Adhesive Bonding, Eutectic Bonding,

FEATURES AND OPTIONS

TRUE VERTICAL TECHNOLOGY™ with 95mm Z-movement

Time/Pressure dispenser, stamping or preform spindle

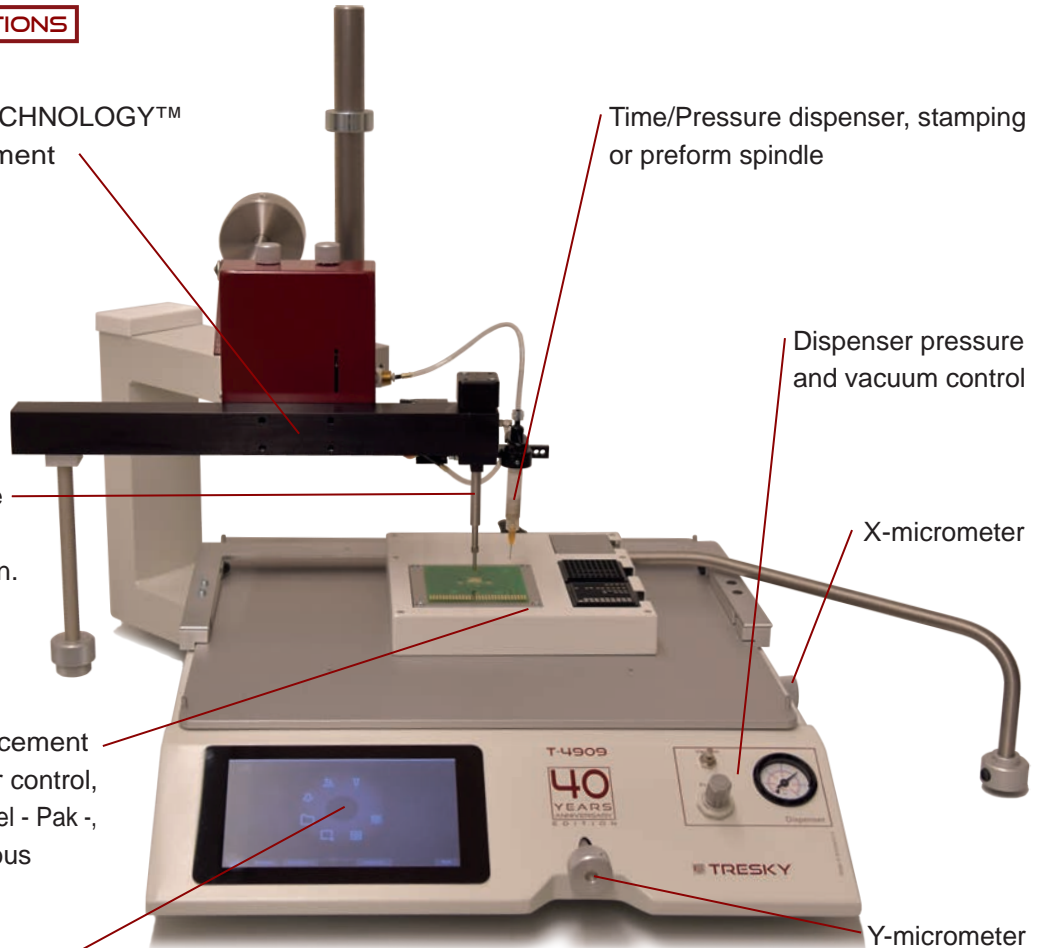
Dispenser pressure and vacuum control

Pick & place spindle with force sensor and 360° tool rotation. Optional: with tool heating and Scrub

X-micrometer

XY air-cushioned placement stage with micrometer control, supporting: Waffle - / Gel - Pak -, Substrate - Holder, various Heating Plates.

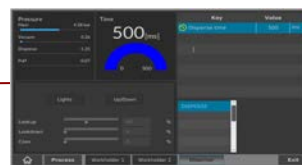
Y-micrometer



Main screen
Touchscreen for selection of pick & place, dispensing, stamping, mode.
Create and store custom sequence.
E.g.: Pick, dispense and place with automatic start of heating.



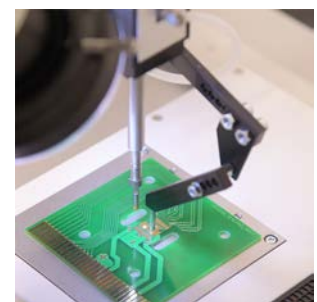
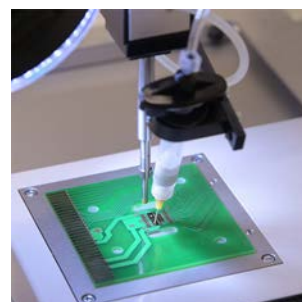
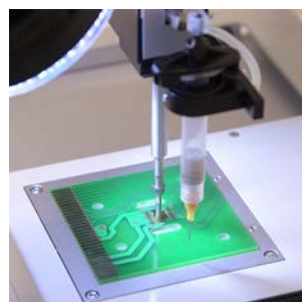
Pick & place mode
for selection pick & place bond force and time



Dispensing mode
for selection of dispensing parameters

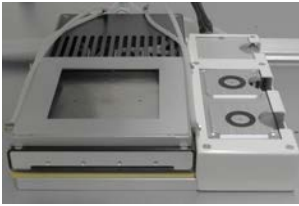


Stamping mode
for selection of stamping parameters

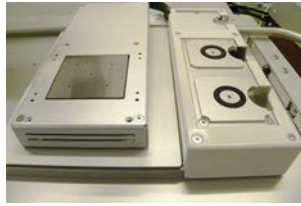


HEATING / EUTECTIC

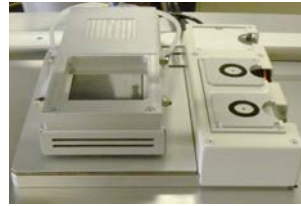
Tresky offers a large variety of standard and customized modules for heated / eutectic processes.



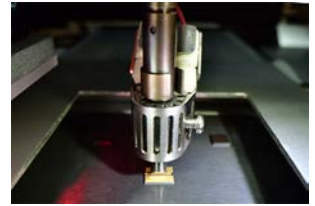
Static heating plate
62x62mm or 100x100mm,
up to 450°C, chamber for
forming gas



Dynamic heating plate
52x52mm or 100x100mm,
up to 400°C



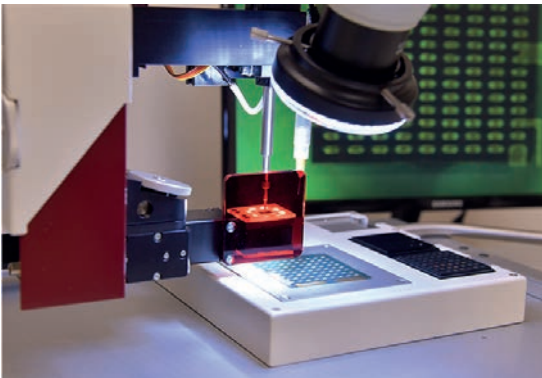
Dynamic heating plate
52x52mm or 100x100mm,
up to 400°C, chamber for
forming gas



Tool heating
up to 450°C

T-4909-AE WITH BEAM-SPLITTER OPTICS (FLIP-CHIP-OPTIC)

Tresky's **FLIP-CHIP ULTRA** module is a beam splitter optic assembly, which allows the simultaneous viewing of two objects by an optical overlay (superposition) on the monitor. The Flip-Chip optics has a built-in Ultra HD camera with digital magnification as well as integrated LED lights for optimal illumination of various substrates and components. In combination with the high magnification and the XY- fine positioning facility, high accuracy alignment can be reached. The module is mounted on the Z-arm which allows movement and focus at various bonding heights. The software displays the overlaid image and is very easy to use.



TECHNICAL SPECIFICATION:

- 400x digital zoom Ultra HD camera
- Field of view 1,2 x 0.9mm – 6,5 x 4.9mm
- Multi point alignment 30mm x 10mm
- LED illumination (up, down and coax)



TECHNICAL DATA

XY- Movement (placement stage):	180mm x 180mm (manual)
Z- Movement:	95mm (manual)
Spindle Rotation:	360° (unlimited)
Bond Force:	20g - 1000g
Placement accuracy:	±10µm (operator/process depending)
Flip-Chip Placement accuracy:	±5µm Option (operator/process depending)
Connections:	Compressed air 5 - 6 bar / Vacuum 0.6 bar (abs)
Dimensions:	755mm x 730mm x 500mm
Weight:	33kg
Voltage:	110V / 220V

TRESKY - SOLUTIONS FOR MICROELECTRONICS ASSEMBLY

Dr. Tresky AG offers manual and semi-manual Die Bonding solutions for small and medium sized electronics assembly facilities, laboratories and R&D.

As a solutions provider, we support specific applications with our highly accurate and innovative systems. Starting from manual to semi automatic, from adhesives to tools, exactly as per our customer's need. This is made possible by our extensive experience and modular setup which allows adapting various basic systems with an huge selection of options for new processes.

With almost 2000 devices installed across the world, often with special & customized equipment, we diligently work to fulfill complex process requirements. Supported by a fast, flexible and professional team ready to be tested, we look forward to your challenge!

We invite you to discover our range of Die Bonding solutions, tools and services.

Note: All specifications are subject to change without notice

Represented by

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